LNJ923W8CRA1

Hight Bright Surface Mounting Chip LED

SV (Side View) Type

■ Absolute Maximum Ratings $T_a = 25$ °C

| Parameter | Symbol | Rating | Unit | |
|-------------------------------|------------------|-------------|------|--|
| Power dissipation | P_{D} | 90 | mW | |
| Forward current | I_F | 25 | mA | |
| Pulse forward current * | I_{FP} | 70 | mA | |
| Reverse voltage | V _R | 5 | V | |
| Operating ambient temperature | T _{opr} | -30 to +85 | °C | |
| Storage temperature | T _{stg} | -40 to +100 | °C | |

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

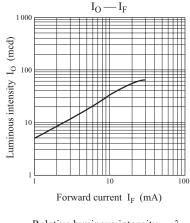
■ Lighting Color

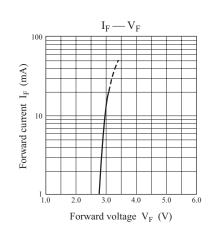
• Blue

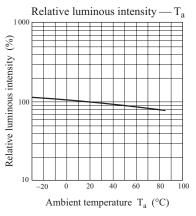
■ Electro-Optical Characteristics $T_a = 25$ °C

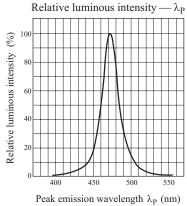
| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|---------------------------------|------------------------|----------------------|------|-----|------|------|
| Luminous intensity *1 | I _O | $I_F = 5 \text{ mA}$ | 10 | 18 | 32 | mcd |
| Reverse current | I_R | $V_R = 5 V$ | | | 100 | μΑ |
| Forward voltage | $V_{\rm F}$ | $I_F = 5 \text{ mA}$ | 2.65 | 2.9 | 3.20 | V |
| Dominant emission wavelength *2 | λ_{d} | $I_F = 5 \text{ mA}$ | 474 | 477 | 481 | nm |
| Peak emission wavelength | λ_{P} | $I_F = 5 \text{ mA}$ | | 472 | | nm |
| Spectral half band width | Δλ | $I_F = 5 \text{ mA}$ | | 20 | | nm |

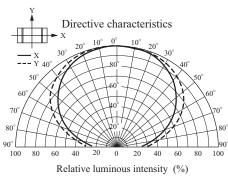
Note) *1: Measurement tolerance: ±20% *2: Measurement tolerance: ±3 nm

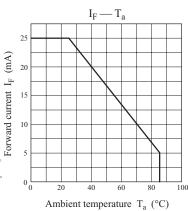




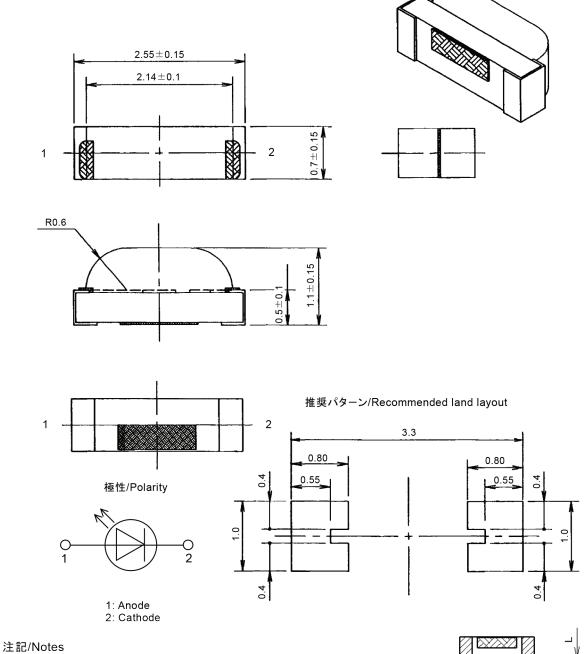








■ Package (Unit: mm)



1.パッケージ寸法については電極バリを含まない。

Package dimensions don't include electrode projection.

2.当製品は、工法上、はんだ付け面端子端部にめっきバリカエリが発生することや、製品背面部に端子を有する 縦型面実装タイプである為、リフローはんだ付けの際、不濡れ等が懸念されます。

従いまして、はんだの種類の検討ならびに各パットに対し、適正なはんだ量を考慮して塗布してください。 Precaution to soldering

Assembly conditions such like mechanical lode in placing LED and also suitable volume and type of solder paste has to be fully investigated.

Insufficient soldering may occur because of the condition of solder terminal surface which is caused is caused by its unique production process.

3.基本的に LED 直下範囲には、固着フットパターン厚み L 以上のシルク印刷をしないでください。 Measurement of the package doesn't include electrode projection.

2 Ver. BEK

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